

Welcome to **THE GLOBAL COLLABORATORY™**



**TOGETHER
WE CAN BUILD THE FUTURE OF PACKAGING**

PACK EXPO INTERNATIONAL - CHICAGO

McCormick Place, S501

NOVEMBER 2 – 5, 2014

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We're excited to be at Pack Expo. **Visit us in our Global Collaboratory in S501.**

DuPont technical experts and partner companies will be discussing various topics related to today's packaging trends and issues. We'll be holding a series of thought-provoking discussions in our Collaboratory about food safety and security, DuPont Awards for Packaging Innovation and current packaging technologies.



MONDAY

"Not Your Average Technology Talk"

Noon to 1:30 p.m.

Join DuPont and partner companies as we explore some of the most frequently asked questions related to today's packaging technologies. Topics include micro-foamed layers in cast coextruded film, water-quenched coextruded blown film, high-pressure pasteurization, and co-injection molding.

Co-hosts: David Dean, Research & Development Director, DuPont Packaging

Bill Cunningham, North America Packaging Director, DuPont Packaging
Light lunch provided.

DuPont Leader Talks Food Safety
1:15 to 1:45 p.m. - Booth #2962
Food Safety Summit Resource Center



Yasmin Siddiqi, Global Packaging Leader, DuPont Packaging, discusses today's food safety challenges and the role packaging can play.

**DuPont sponsors
PACK gives BACK™ Event**
4:30 to 6:15 p.m. - S100

PACK gives BACK™ is one of the signature events of Pack Expo. The event offers an opportunity for show registrants to collectively "give back" to a worthwhile cause - K9s for Warriors. Tickets required.



TUESDAY

"Packaging Value Chain Collaborates to Mitigate Food Waste"

9:30 to 11:00 a.m.



Panel discussion with members of PAC (The Packaging Association) discussing the role of packaging and the importance of global collaboration in addressing food waste. Features speakers from PAC, Unilever, Sealed Air, and DuPont.

"From Body Armor to Packaging"

Noon to 1:00 p.m.



Want to save your packages from being punctured in the filling line? Find out how DuPont extended its computer model for body armor to build a model for evaluating puncture performance of packaging. Learn how to be a hero for your packages.

Presenter: Diane Hahm, Senior Technical Consultant, DuPont Packaging
Light lunch provided.

WEDNESDAY

"Honoring Packaging Innovation"

10:00 to 11:00 a.m.

Join us as we announce our 2015 Call for Entries for the DuPont Awards for Packaging Innovation and our new advisory panel.

Also, learn how to submit a winning entry for your company.

Don't miss this opportunity to learn more about the industry's longest-running, independently-judged packaging competition and why it is important for your company to celebrate innovation.



Presenters: Yasmin Siddiqi, Global Packaging Leader, DuPont Packaging & David Luttenberger, Global Packaging Director, Mintel Group

For more details about our presentations, see us at **S501** or visit packexpo.dupont.com

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